



Advancements in Nanofabrication: Innovations in Advanced Semiconductor Materials and Processes for Next-Generation Lithography

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Message from the Guest Editors

Scope:

We invite contributions that delve into the forefront of nanofabrication technologies, emphasizing advancements in semiconductor materials and processes that directly impact next-generation lithography methods.

Potential Themes:

Advanced Semiconductor Materials: Explore the latest developments in semiconductor materials such as advanced photoresists, high-index materials, and alternative lithographic materials.

Innovative Lithographic Techniques: Investigate novel approaches and methodologies in lithography, including extreme ultraviolet (EUV) lithography, directed self-assembly, and other emerging techniques.

Process Optimization and Integration: Address challenges and breakthroughs in optimizing nanofabrication processes, as well as strategies for the seamless integration of advanced materials into existing fabrication workflows.

Applications in Emerging Technologies: Showcase the practical applications of nanofabrication innovations in areas such as quantum computing, photonics, bioelectronics, and other cutting-edge technologies.